

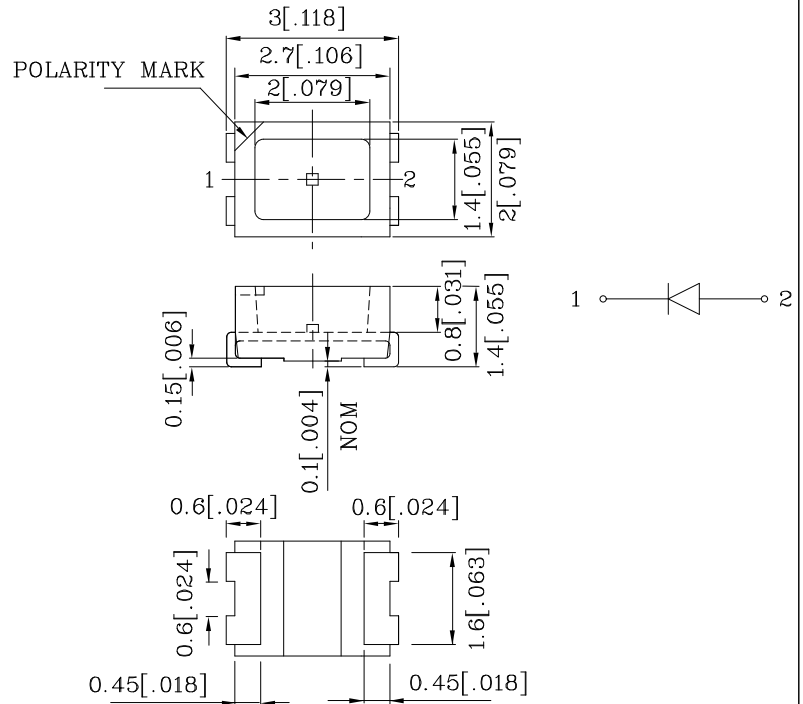
**Features**

- 3.0MM X 2.0MM, 1.4MM HIGH, ONLY MINIMUM SPACE REQUIRED.
- SUITABLE FOR COMPACT OPTOELECTRONIC APPLICATIONS.
- LOW POWER CONSUMPTION.
- PACKAGE : 2000PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- RoHS COMPLIANT.



Notes:

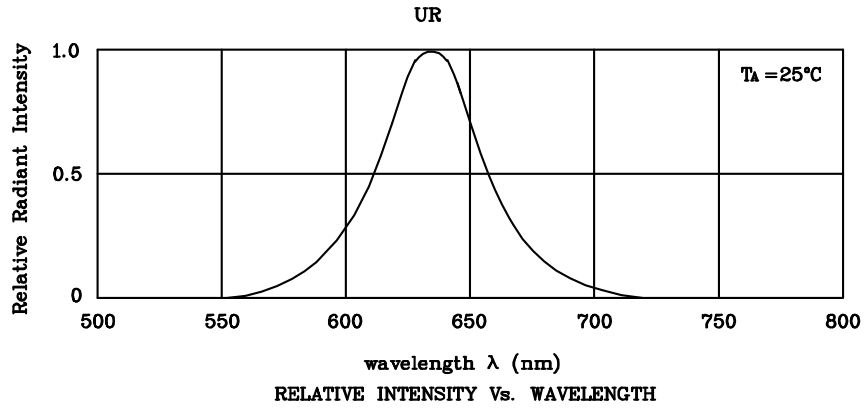
1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01)$ " unless otherwise noted.
3. Specifications are subject to change without notice.



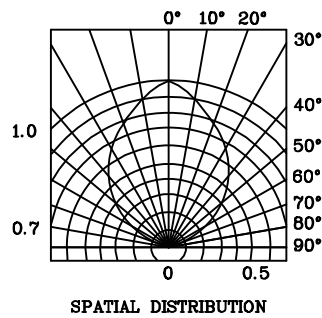
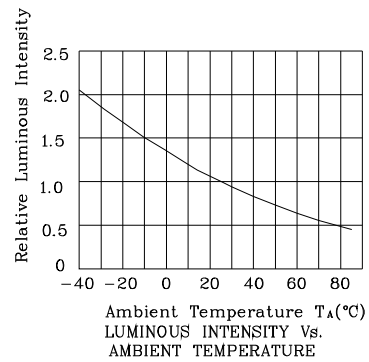
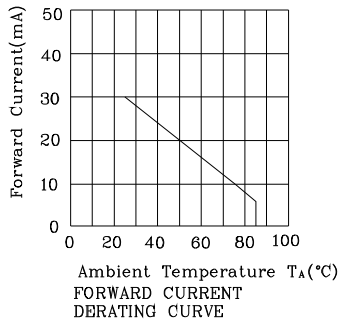
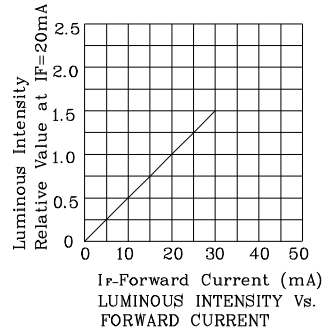
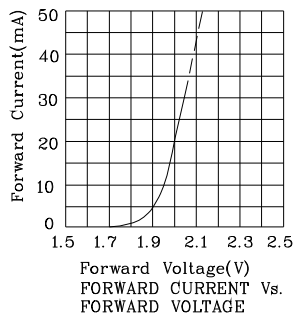
Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ )		UR (GaAsP/GaP)	Unit
Reverse Voltage	$V_R$	5	V
Forward Current	$I_F$	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	$i_{FS}$	160	mA
Power Dissipation	$P_T$	75	mW
Operating Temperature	$T_A$	-40 ~ +85	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-40 ~ +85	

Operating Characteristics ( $T_A=25^\circ\text{C}$ )		UR (GaAsP/GaP)	Unit
Forward Voltage (Typ.) ( $I_F=20\text{mA}$ )	$V_F$	2.0	V
Forward Voltage (Max.) ( $I_F=20\text{mA}$ )	$V_F$	2.5	V
Reverse Current (Max.) ( $V_R=5\text{V}$ )	$I_R$	10	$\mu\text{A}$
Wavelength of Peak Emission (Typ.) ( $I_F=20\text{mA}$ )	$\lambda_P$	627	nm
Wavelength of Dominant Emission (Typ.) ( $I_F=20\text{mA}$ )	$\lambda_D$	625	nm
Spectral Line Full Width At Half-Maximum (Typ.) ( $I_F=20\text{mA}$ )	$\Delta\lambda$	45	nm
Capacitance (Typ.) ( $V_F=0\text{V}$ , $f=1\text{MHz}$ )	$C$	15	pF

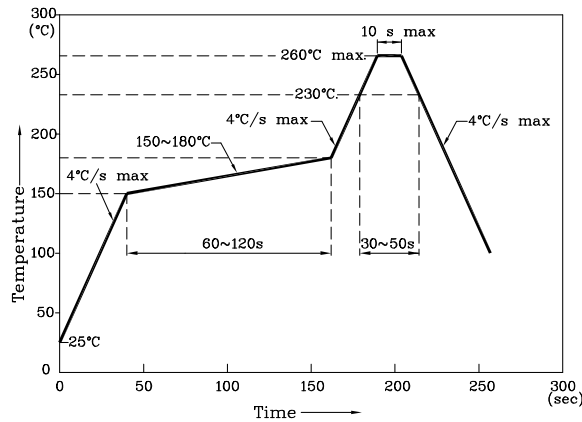
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity ( $I_F=20\text{mA}$ ) mcd		Wavelength nm $\lambda_P$	Viewing Angle $2\theta$ 1/2
				min.	typ.		
ZUR50FW	Red	GaAsP/GaP	Water Clear	7	19	627	$90^\circ$
Published Date : FEB 26, 2008      Drawing No : SDSA6337      V1      Checked : B.L.LIU      P.1/4							



❖ **UR**



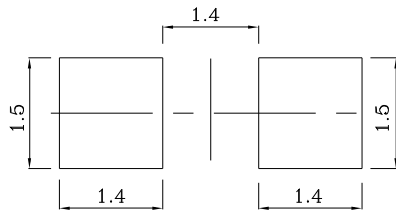
Reflow Soldering Profile For Lead-free SMT Process.



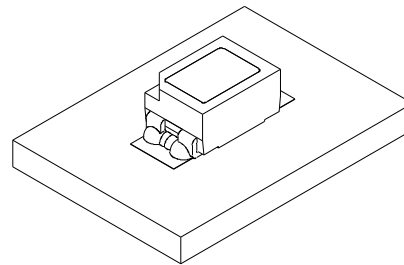
NOTES:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

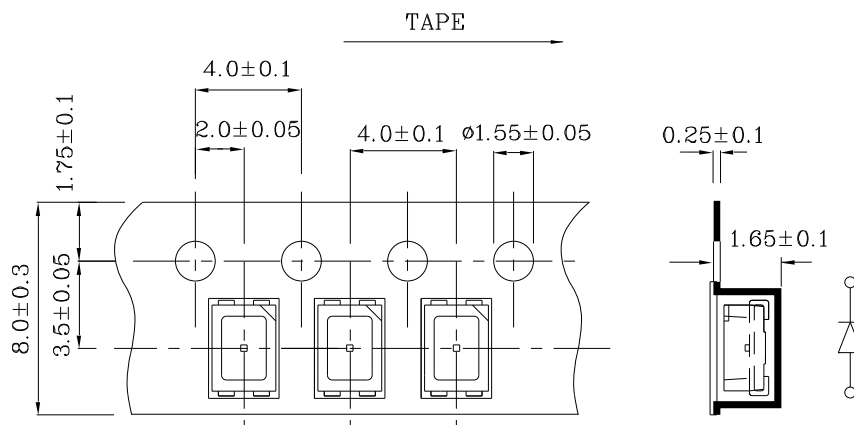
❖ Recommended Soldering Pattern  
(Units : mm; Tolerance:± 0.1)



❖ The device has a single mounting surface. The device must be mounted according to the specifications.



❖ Tape Specification (Units : mm)



Remarks:

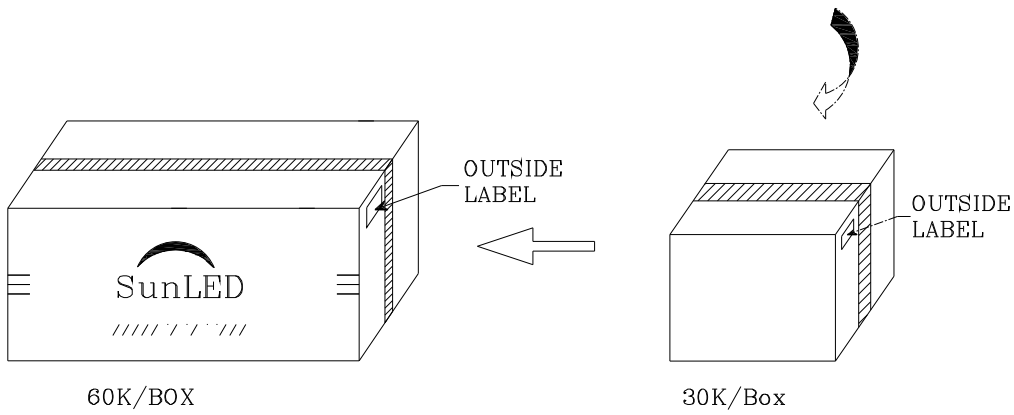
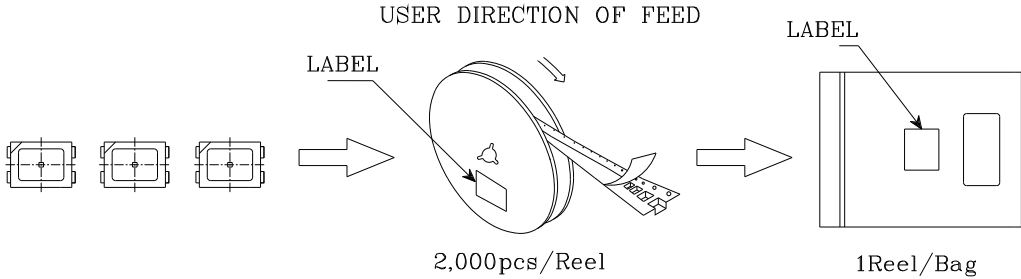
If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:


1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

**PACKING & LABEL SPECIFICATIONS**

**ZUR50FW**



P/NO : Zxx50Fx	
QTY : 2,000 pcs	CODE: XXX
S/N : XX	
LOT NO:	
 xxxxxxxxxxxxxxxxxxxxxxxx	
RoHS Compliant	